TLV4011 Precision Comparator with Integrated Reference

1 Features
- Adjustable thresholds down to 1.226 V
- Precision ±1.5% threshold voltage accuracy
- Supply current: 3 μA
- Open-drain output
- Temperature range: –40°C to 85°C
- 5-Pin SC-70 package

2 Applications
- Electricity meters
- Circuit breakers
- Thermostats
- Cordless power tools

3 Description
The TLV4011 is a low-power, high-accuracy comparator with a precision, integrated reference. Two external resistors can be connected to the input to create an adjustable voltage threshold down to 1.226 V.

The factory-trimmed switching threshold and precision hysteresis combine to make the TLV4011 appropriate for voltage and current monitoring in harsh, noisy environments where slow moving input signals must be converted into clean digital outputs. Similarly, brief glitches on the input are rejected thereby ensuring stable output operation without false triggering.

During power on, RESET is asserted (LOW) when the supply voltage $V_{DD}$ becomes higher than 0.8 V. Thereafter, the TLV4011 monitors the input and keeps RESET active (LOW) while the input remains below the threshold voltage $V_{IT}$. As soon as the input rises above the threshold voltage $V_{IT}$, RESET is deasserted (HIGH). The product spectrum is designed for 1.8-V, 3.3-V, 5-V, and adjustable supply voltages.

The TLV4011 is available in a 5-pin SC-70 package and are characterized for operation over a temperature range of –40°C to 85°C.

Device Information

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>TLV4011</td>
<td>SC-70 (5)</td>
<td>2.00 mm x 1.25 mm</td>
</tr>
</tbody>
</table>

(1) For all available packages, see the orderable addendum at the end of the data sheet.
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4 Revision History

<table>
<thead>
<tr>
<th>DATE</th>
<th>REVISION</th>
<th>NOTES</th>
</tr>
</thead>
<tbody>
<tr>
<td>March 2020</td>
<td></td>
<td>Initial release</td>
</tr>
</tbody>
</table>
5 Pin Configuration and Functions

<table>
<thead>
<tr>
<th>PIN</th>
<th>I/O</th>
<th>DESCRIPTION</th>
</tr>
</thead>
<tbody>
<tr>
<td>NAME</td>
<td>NO.</td>
<td>I/O</td>
</tr>
<tr>
<td>GND</td>
<td>2</td>
<td>I</td>
</tr>
<tr>
<td>RESET</td>
<td>3</td>
<td>O</td>
</tr>
<tr>
<td>SENSE</td>
<td>5</td>
<td>I</td>
</tr>
<tr>
<td>NC</td>
<td>1</td>
<td>—</td>
</tr>
<tr>
<td>V_{DD}</td>
<td>4</td>
<td>I</td>
</tr>
</tbody>
</table>
6 Specifications

6.1 Absolute Maximum Ratings
over operating free-air temperature range (unless otherwise noted)\(^1\)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{DD}) Supply voltage(^{(2)})</td>
<td>–0.3</td>
<td>7</td>
<td>V</td>
</tr>
<tr>
<td>Voltage applied to all other pins(^{(2)})</td>
<td>–0.3</td>
<td>7</td>
<td>V</td>
</tr>
<tr>
<td>(I_{OL}) Maximum low-level output current</td>
<td>5</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>(I_{OH}) Maximum high-level output current</td>
<td>–5</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>(I_{IK}) Input clamp current (V_i &lt; 0) or (V_i &gt; V_{DD})</td>
<td>±10</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>(I_{OK}) Output clamp current (V_O &lt; 0) or (V_O &gt; V_{DD})</td>
<td>±10</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>(P_D) Continuous total power dissipation</td>
<td>See Dissipation Ratings</td>
<td></td>
<td></td>
</tr>
<tr>
<td>(T_A) Operating free-air temperature</td>
<td>–40</td>
<td>85</td>
<td>°C</td>
</tr>
<tr>
<td>(T_{solder}) Soldering temperature</td>
<td>–65</td>
<td>260</td>
<td>°C</td>
</tr>
</tbody>
</table>

\(^1\) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

\(^2\) All voltage values are with respect to GND. For reliable operation, the device should not be continuously operated at 7 V for more than \(t = 1000\) h.

6.2 ESD Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{(ESD)}) Electrostatic discharge</td>
<td>±2000</td>
<td>V</td>
</tr>
<tr>
<td>Human body model (HBM), per ANSI/ESDA/JEDEC JS-001(^{(1)})</td>
<td>±1000</td>
<td>V</td>
</tr>
<tr>
<td>Charged-device model (CDM), per JEDEC specification JESD22-C101(^{(2)})</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

\(^1\) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

\(^2\) JEDEC document JEP155 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{DD}) Supply voltage</td>
<td>1.3</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>(V_i) Input voltage</td>
<td>0</td>
<td>(V_{DD} + 0.3)</td>
<td>V</td>
</tr>
<tr>
<td>(T_A) Operating free-air temperature</td>
<td>–40</td>
<td>85</td>
<td>°C</td>
</tr>
</tbody>
</table>

6.4 Thermal Information

<table>
<thead>
<tr>
<th>Thermal Metric(^{(1)})</th>
<th>TLV4011 DCK (SC-70)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Junction-to-ambient thermal resistance</td>
<td>246.6</td>
</tr>
<tr>
<td>Junction-to-case (top) thermal resistance</td>
<td>68.2</td>
</tr>
<tr>
<td>Junction-to-board thermal resistance</td>
<td>78.4</td>
</tr>
<tr>
<td>Junction-to-top characterization parameter</td>
<td>0.9</td>
</tr>
<tr>
<td>Junction-to-board characterization parameter</td>
<td>77.7</td>
</tr>
<tr>
<td>Junction-to-case (bottom) thermal resistance</td>
<td>N/A</td>
</tr>
</tbody>
</table>

\(^1\) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPRA953.
6.5 Electrical Characteristics
over operating free-air temperature range (unless otherwise noted)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{OL}$ Low-level output voltage</td>
<td>$V_{DD} = 1.5 \text{ V, } I_{OL} = 1 \text{ mA}$</td>
<td></td>
<td></td>
<td>0.3</td>
<td>V</td>
</tr>
<tr>
<td></td>
<td>$V_{DD} = 3.3 \text{ V, } I_{OL} = 2 \text{ mA}$</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td></td>
<td>$V_{DD} = 6 \text{ V, } I_{OL} = 3 \text{ mA}$</td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>$V_{POR}$ Power-up reset voltage</td>
<td>$V_{OL}^{(max)} = 0.2 \text{ V, } I_{OL} = 50 \text{ μA, } T_{A} = 25^\circ \text{C}$</td>
<td></td>
<td>0.8</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>$V_{IT}$ Negative-going input threshold voltage</td>
<td>SENSE</td>
<td>1.2</td>
<td>1.226</td>
<td>1.244</td>
<td>V</td>
</tr>
<tr>
<td>$V_{HY}$ Hysteresis</td>
<td>$T_{A} = 25^\circ \text{C}$</td>
<td></td>
<td></td>
<td>15</td>
<td>mV</td>
</tr>
<tr>
<td>$I_{i}$ Input current</td>
<td>SENSE</td>
<td>$-25$</td>
<td></td>
<td>25</td>
<td>nA</td>
</tr>
<tr>
<td>$I_{IH}$ High-level output current at RESET</td>
<td>$V_{DD} = 3.3 \text{ V, Output unconnected}$</td>
<td>2</td>
<td></td>
<td>4</td>
<td>μA</td>
</tr>
<tr>
<td></td>
<td>$V_{DD} = 6 \text{ V, Output unconnected}$</td>
<td>2</td>
<td></td>
<td>4</td>
<td>μA</td>
</tr>
<tr>
<td>$C_{i}$ Input capacitance</td>
<td>$V_{i} = 0 \text{ V to } V_{DD}$</td>
<td>1</td>
<td></td>
<td></td>
<td>pF</td>
</tr>
</tbody>
</table>

(1) The lowest supply voltage at which $V_{OL}$ becomes active. $t_{(V_{DD})} \leq 15 \mu \text{S/V}$.
(2) To ensure the best stability of the threshold voltage, place a bypass capacitor (ceramic, 0.1-μF) near the supply terminals.

6.6 Timing Requirements

$R_{L} = 1 \text{ M}\Omega, C_{L} = 50 \text{ pF, } T_{A} = -40^\circ \text{C to 85}^\circ \text{C}$ (unless otherwise noted)

| $t_{w}$ Pulse duration | SENSE | $V_{IH} = 1.05 \times V_{IT}, V_{IL} = 0.95 \times V_{IT}$ | 5.5 | μs |

6.7 Switching Characteristics

$R_{L} = 1 \text{ M}\Omega, C_{L} = 50 \text{ pF, } T_{A} = -40^\circ \text{C to 85}^\circ \text{C}$ (unless otherwise noted)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>$t_{PHL}$ Propagation (delay) time, high-to-low-level output</td>
<td>SENSE to RESET delay</td>
<td>$V_{IH} = 1.05 \times V_{IT}, V_{IL} = 0.95 \times V_{IT}$</td>
<td>5</td>
<td>100</td>
<td>μs</td>
</tr>
<tr>
<td>$t_{PLH}$ Propagation (delay) time, low-to-high-level output</td>
<td>SENSE to RESET delay</td>
<td>$V_{IH} = 1.05 \times V_{IT}, V_{IL} = 0.95 \times V_{IT}$</td>
<td>5</td>
<td>100</td>
<td>μs</td>
</tr>
</tbody>
</table>

6.8 Dissipation Ratings

<table>
<thead>
<tr>
<th>PACKAGE</th>
<th>POWER RATING $T_{A} = 25^\circ \text{C}$</th>
<th>DERATING FACTOR ABOVE $T_{A} = 25^\circ \text{C}$</th>
<th>POWER RATING $T_{A} = 70^\circ \text{C}$</th>
<th>POWER RATING $T_{A} = 85^\circ \text{C}$</th>
</tr>
</thead>
<tbody>
<tr>
<td>DCK</td>
<td>321 mW</td>
<td>2.6 mW/°C</td>
<td>206 mW</td>
<td>167 mW</td>
</tr>
</tbody>
</table>
Figure 1. Timing Requirements
6.9 Typical Characteristics

Figure 2. Supply Current vs Supply Voltage

Figure 3. Low-Level Output Voltage vs Low-Level Output Current

Figure 4. Low-Level Output Voltage vs Low-Level Output Current

Figure 5. Low-Level Output Voltage vs Low-Level Output Current

Figure 6. Low-Level Output Voltage vs Low-Level Output Current

Figure 7. Normalized Input Threshold Voltage vs Free-Air Temperature At Sense
7 Detailed Description

7.1 Overview
The TLV4011 is a low-current comparator used to monitor system voltages above 1.226 V. The comparators assert an active low RESET signal when the SENSE voltages drop below VIT. The RESET output remains low until the SENSE voltage returns above VIT plus the integrated hysteresis level. The TLV4011 is also designed to be immune to short negative transients on the SENSE pin.

7.2 Functional Block Diagram

![Functional Block Diagram](image)

7.3 Feature Description

7.3.1 SENSE Monitoring
The SENSE input is where a system voltage can be monitored. If the voltage on this pin drops below $V_{IT}$, RESET is asserted low. The comparator has a built-in hysteresis to ensure smooth RESET assertions and de-assertions. By connecting a resistor divider network to the SENSE input as shown in the circuit below, VIN is divided down so RESET will assert when the divided down value of VIN reaches VIT (1.226 V). The TLV4011 is capable of monitoring any input voltage down to 1.226 V.

![Circuit Diagram](image)
Feature Description (continued)

7.3.2 Transient Immunity

The TLV4011 is immune to short negative transients on the SENSE pin. Sensitivity to transients is dependent on threshold overdrive as shown in Figure 9 and Figure 10. These graphs show the duration that the transient is below $V_{IT}$ compared to the magnitude of the voltage drop below $V_{IT}$, called the threshold overdrive voltage. Any combination of transient duration and overdrive voltage which lies above the curves will result in $\text{RESET}$ being asserted low. Any transient which lies below the curves will be ignored by the device.

![Figure 9. SENSE Overdrive Voltage](image)

![Figure 10. Minimum Pulse Duration at Sense vs Sense Threshold Overdrive Voltage](image)

7.4 Device Functional Modes

The SENSE input is used to monitor one supply. When that supply is above the $V_{IT}$ threshold, $\text{RESET}$ will be high. Otherwise, $\text{RESET}$ will be low.

<table>
<thead>
<tr>
<th>Table 1. Function and Truth</th>
</tr>
</thead>
<tbody>
<tr>
<td><strong>TLV4011</strong></td>
</tr>
<tr>
<td><strong>SENSE &gt; $V_{IT}$</strong></td>
</tr>
<tr>
<td>0 (False)</td>
</tr>
<tr>
<td>1 (True)</td>
</tr>
</tbody>
</table>
8 Application and Implementation

NOTE
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 Application Information
The TLV4011 comparator is designed to assert an active-low \texttt{RESET} signal when the SENSE input drops below the voltage threshold \( V_{\text{IT}} \). The \texttt{RESET} signal remains low until the voltages return above their respective threshold plus the hysteresis. If additional hysteresis is required, positive feedback can be implemented similar to how it is done on a discrete comparator. See Application Note for details on how to implement external hysteresis in a non-inverting configuration.

8.2 Typical Application

8.2.1 Under-Voltage Detection
Under-voltage detection is frequently required in battery-powered, portable electronics to alert the system that a battery voltage has dropped below the usable voltage level. Figure 11 shows a simple under-voltage detection circuit using the TLV4011 which is a non-inverting comparator with an integrated 1.226 V reference and an open-drain output stage. A non-inverting is well suited for this application since the micro-controller requires an active low signal when an undervoltage level occurs.

\begin{figure}[h]
\centering
\includegraphics[width=0.5\textwidth]{figure11.pdf}
\caption{Under-Voltage Detection}
\end{figure}

8.2.1.1 Design Requirements
For this design, follow these design requirements:
• TLV4011 operates from the \( V_{\text{BAT}} \) directly
• Output is level-shifted to the 3.3 V power supply that powers the microcontroller.
• Under-voltage alert is active low.
• Logic low output when \( V_{\text{BAT}} \) decreases below 2.0V.

8.2.1.2 Detailed Design Procedure
Configure the circuit as shown in Figure 11. Note that VDD of the comparator is connected directly to \( V_{\text{BAT}} \) (the battery being monitored) and the output of the comparator is level shifted with its open-drain output to 3.3 V which powers the micro-controller. Resistors \( R_1 \) and \( R_2 \) divide down \( V_{\text{BAT}} \) so that the resistor divided output equals 1.226 V when \( V_{\text{BAT}} \) reaches an under-voltage alert level of 2.0 V.
Typical Application (continued)

When the battery voltage sags down to 2.0 V, the resistor divider voltage crosses the \( V_{\text{IT}} = 1.226 \text{ V} \) threshold of the TLV4011. This causes the comparator output to transition from a logic high to a logic low. An open-drain comparator is selected so the comparator output is compatible with the input logic level of the microcontroller. In addition, selecting a comparator with an integrated reference value of 1.226 V is favorable because it is the closest internal reference option that is less than the critical under-voltage level of 2.0 V. Choosing the internal reference option that is closest to the critical under-voltage level minimizes the resistor divider ratio which optimizes the accuracy of the circuit. Error at the falling edge threshold of \( V_{\text{IT}} \) is amplified by the inverse of the resistor divider ratio. So minimizing the resistor divider ratio is a way of optimizing voltage monitoring accuracy.

Equation 1 is derived from the analysis of Figure 11.

\[
V_{\text{IT}} = \frac{R_2}{R_1 + R_2} \times V_{\text{BAT}}
\]  

(1)

where

- \( R_1 \) and \( R_2 \) are the resistor values for the resistor divider connected to SENSE
- \( V_{\text{BAT}} \) is the voltage source that is being monitored for an undervoltage condition.
- \( V_{\text{IT}} \) is the falling edge threshold where the comparator output changes state from high to low

Rearranging Equation 1 and solving for \( R_1 \) yields Equation 2.

\[
R_1 = \left( \frac{V_{\text{BAT}} - V_{\text{IT}}}{V_{\text{IT}}} \right) \times R_2
\]

(2)

For the specific undervoltage detection of 2.0 V using the TLV4011, the following results are calculated.

\[
R_1 = \left( \frac{2.0 - 1.226}{1.226} \right) \times 1\text{M} = 631 \text{k}\Omega
\]

(3)

where

- \( R_2 \) is set to 1 M\( \Omega \)
- \( V_{\text{BAT}} \) is set to 2.0 V
- \( V_{\text{IT}} \) is set to 1.226 V

Choose \( R_{\text{TOTAL}}(R_1 + R_2) \) such that the current through the divider is at approximately 100 times higher than the input bias current (\( I_{\text{BIAS}} \)). The resistors can have high values to minimize current consumption in the circuit without adding significant error to the resistive divider.

8.2.1.3 Application Curve

![Figure 12. Under-Voltage Detection](image-url)
Typical Application (continued)

8.2.2 Additional Application Information

8.2.2.1 Pull-up Resistor Selection

Since the TLV4011 has an open drain output, care should be taken in selecting the pull-up resistor (R\text{\textsubscript{PU}}) value to ensure proper output voltage levels. First, consider the required output high logic level requirement of the logic device that is being driven by the comparator when calculating the maximum R\text{\textsubscript{PU}} value. When in a logic high output state, the output impedance of the comparator is very high but there is a finite amount of leakage current that needs to be accounted for. Use I\text{\textsubscript{OH}} from the EC Table and the V\textsubscript{IH} minimum from the logic device being driven to determine R\text{\textsubscript{PU}} maximum using Equation 4.

\[
R_{\text{PU}}(\text{max}) = \frac{V_{\text{PU}} - V_{\text{IH(min)}}}{I_{\text{OH}}}
\]

(4)

Next, determine the minimum value for R\text{\textsubscript{PU}} by using the V\textsubscript{IL} maximum from the logic device being driven. In order for the comparator output to be recognized as a logic low, V\textsubscript{IL} maximum is used to determine the upper boundary of the comparator’s V\textsubscript{OL}. V\textsubscript{OL} maximum for the comparator is available in the EC Table for specific sink current levels and can also be found from the V\textsubscript{OUT} versus I\textsubscript{SINK} curve in the Typical Application curves. A good design practice is to choose a value for V\textsubscript{OL} maximum that is 1/2 the value of V\textsubscript{IL} maximum for the input logic device. The corresponding sink current and V\textsubscript{OL} maximum value will be needed to calculate the minimum R\text{\textsubscript{PU}}. This method will ensure enough noise margin for the logic low level. With V\textsubscript{OL} maximum determined and the corresponding I\textsubscript{SINK} obtained, the minimum R\text{\textsubscript{PU}} value is calculated with Equation 5.

\[
R_{\text{PU}}(\text{min}) = \frac{V_{\text{PU}} - V_{\text{OL(max)}}}{I_{\text{SINK}}}
\]

(5)

Since the range of possible R\text{\textsubscript{PU}} values is large, a value between 5 kΩ and 100 kΩ is generally recommended. A smaller R\text{\textsubscript{PU}} value provides faster output transition time and better noise immunity, while a larger R\text{\textsubscript{PU}} value consumes less power when in a logic low output state.

8.2.2.2 Input Supply Capacitor

Although an input capacitor is not required for stability, for good analog design practice, connect a 100 nF low equivalent series resistance (ESR) capacitor from (VDD) to (GND).

8.2.2.3 Sense Capacitor

Although not required in most cases, for extremely noisy applications, place a 1 nF to 100 nF bypass capacitor from the comparator input (SENSE) to the (GND) for good analog design practice. This capacitor placement reduces device sensitivity to transients.

9 Power Supply Recommendations

The TLV4011 comparator is designed to operate from an input supply from 1.3 V to 6 V. It is recommended to place a 0.1-μF capacitor from the VDD pin to GND.
10 Layout

10.1 Layout Guidelines
TI recommends to place the 0.1-µF decoupling capacitor close to the VDD pin. The VDD trace should be able to carry 6 µA without a significant drop in voltage. Avoid a long trace from the SENSE pin to the resistor divider.

10.2 Layout Examples

Figure 13. Layout Example
11 Device and Documentation Support

11.1 Receiving Notification of Documentation Updates
To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

11.2 Support Resources
TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

11.3 Trademarks
E2E is a trademark of Texas Instruments.

11.4 Electrostatic Discharge Caution
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

11.5 Glossary
SLYZ022 — TI Glossary,
   This glossary lists and explains terms, acronyms, and definitions.
12 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
### PACKAGING INFORMATION

<table>
<thead>
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<td>Level-1-260C-UNLIM</td>
<td>-40 to 85</td>
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(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF TLV4011 :**
• Automotive: TLV4011-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
### TAPE AND REEL INFORMATION

- **Device**: TLV4011DCKR
- **Package Type**: SC70
- **Drawing**: DCK
- **Pins**: 5
- **SPQ**: 3000
- **Reel Diameter** (mm): 178.0
- **Reel Width** (W1) (mm): 9.0
- **A0** (mm): 2.4
- **B0** (mm): 2.5
- **K0** (mm): 1.2
- **P1** (mm): 4.0
- **W** (mm): 8.0
- **Pin1 Quadrant**: Q3

*All dimensions are nominal.*

### PACKAGE MATERIALS INFORMATION

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**Device** | **Package Type** | **Drawing** | **Pins** | **SPQ** | **Reel Diameter** (mm) | **Reel Width** (W1) (mm) | **A0** (mm) | **B0** (mm) | **K0** (mm) | **P1** (mm) | **W** (mm) | **Pin1 Quadrant**
--- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | ---
TLV4011DCKR | SC70 | DCK | 5 | 3000 | 178.0 | 9.0 | 2.4 | 2.5 | 1.2 | 4.0 | 8.0 | Q3
### TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal*

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<thead>
<tr>
<th>Device</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>SPQ</th>
<th>Length (mm)</th>
<th>Width (mm)</th>
<th>Height (mm)</th>
</tr>
</thead>
<tbody>
<tr>
<td>TLV4011DCKR</td>
<td>SC70</td>
<td>DCK</td>
<td>5</td>
<td>3000</td>
<td>180.0</td>
<td>180.0</td>
<td>18.0</td>
</tr>
</tbody>
</table>
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
D. Falls within JEDEC MO-203 variation AA.
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
D. Publication IPC-7351 is recommended for alternate designs.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
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